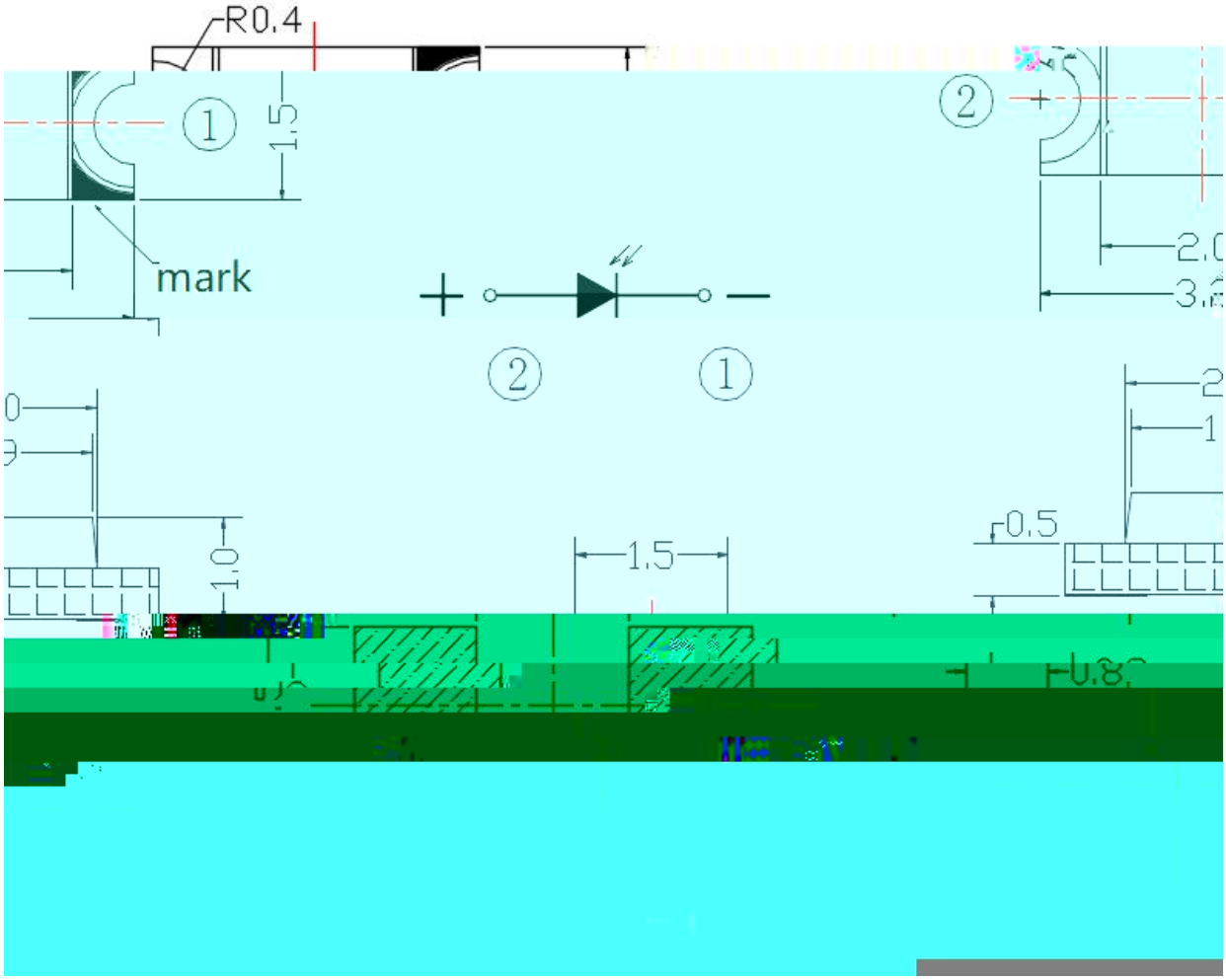
可靠性试验

Reliability Test Items And Conditions

Class	Test item	Testing environment	Testing time	Reference standard
Endurance test	Working life	20mA Continuous lighting at the maximum rated current at room	1000 1000 hours -24 +72) -24hours +72hours	MIL-STD-750D:1026 MIL-STD-883D:1005 JIS C 7021:B-1
	High temperature and high humidity	IR-Reflow In-Board, 2 Times Ta= 85±5 , RH= 90 95%	240 240hours ± 2) ± 2hours)	MIL-STD-202F:103B JIS C 7021:B-11
	High-temperature storage	Ta= 85±5	1000 1000 hours -24 +72) -24hours+72hours	MIL-STD-883D:1008 JIS C 7021:B-10
	Low temperature	Ta= -40±5		JIS C 7021:B-12
	Cold and hot cycle	105 25 -55 25 30mins 5mins 30mins 5mins	100 100 Circles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010
	Hot and cold impact	IR-Reflow In-Board, 2 Times 100± 5 -40 ± 5 20mins 20mins	100 100 Circles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1011
	Anti-tin test	T.sol= 260 ± 5	10 ± 1secs 2 2times	MIL-STD-202F:210A MIL-STD-750D:2031
Environmental testing	Infrared reflowwelding There is lead process	heat up speed(183) 3 / keep temperature 125(±25) 120 keep temperature 183 60-150 maximum temperature 235 +5/-0 keep 235 +5/-0 10-15 cooling rate 6 /	--------	MIL-STD-750D:2031.2 J-STD-020C
	Infrared reflow welding Lead-free process	heat up speed(217) 3 / keep temperature 175(±25) 180 keep temperature 217 60-120 maximum temperature 255 +0/-5 keep 255 +0/-5 5-10 cooling rate 6 /	--------	MIL-STD-750D:2031.2 J-STD-020C
	Weldability test	Soldering temperature T.sol= 235 ± 5 Immersion speed 25±2.5 mm/ 95% Tin loading p		

外形尺寸

Outline Dimension



1. mm

Remarks: 1. Unit: mm

2. ±0.10mm

2.Tolerance: ± 0.10mm unless otherwise specified

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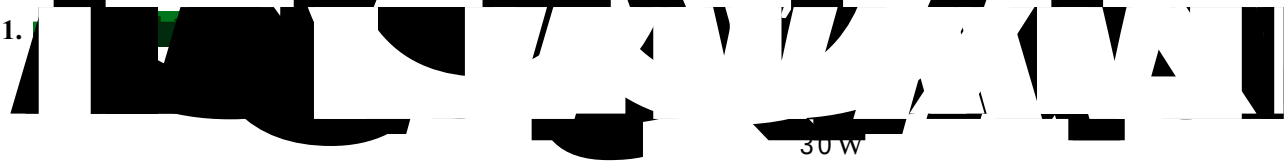
Gu ne for Soldering

1.



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LED

Manual welding is recommended only for repair and heavy industry situations. A soldering iron of less than 30W is recommended to be used in Hand Soldering. Please keep the temperature of the soldering iron under 300 while soldering. Each terminal of the LED is to go for less than 3 second and for one time only.

Be careful because the damage of the product is often started at the time of the hand soldering.

2. 回流焊接：

Use the conditions shown in the under Figure of Pb -Free Reflow Soldering.